

Figure 1 Dimensions	MicroMELF	MiniMELF QuadroMELF	MELF	SOD-323	SOD-123	SOD-523	SMA	SMB	SMC
Z	3.0	4.8	6.3	3.75	4.9	2.3	6.5	6.7	9.3
G	1.4	2.1	3.3	1.05	2.5	1.1	1.5	1.8	4.4
X	1.5	1.7	2.7	0.65	0.7	0.8	1.7	2.3	3.3
Y	0.8	1.3	1.5	1.35	1.2	0.6	2.5	2.5	2.5
C	2.2	3.5	4.8	2.40	3.7	1.7	4.0	4.3	6.8

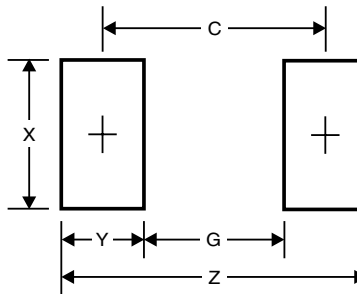


Fig. 1

Figure 2 Dimensions	SOT-523	SOT-323	SOT-23	SC-59
Z	1.9	2.8	3.4	4.0
G	0.9	1.0	0.7	1.2
X	0.5	0.7	0.9	0.9
Y	0.5	0.9	1.4	1.4
C	1.4	1.9	2.0	2.6
E	0.5	0.65	0.9	0.95

Figure 3 Dimensions	SOT-363/SOT-353	SOT-26/SOT-25
Z	2.5	3.20
G	1.3	1.60
X	0.42	0.55
Y	0.6	0.80
C	1.9	2.40
E	0.65	0.95

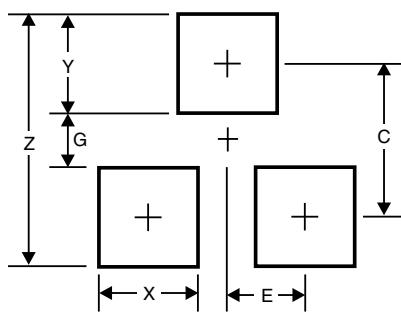


Fig. 2

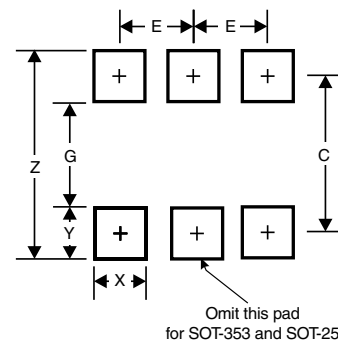


Fig. 3

ALL DIMENSIONS ARE NOMINAL VALUES SHOWN IN MILLIMETERS

Note: The suggested land pattern dimensions have been provided for reference only, as actual pad layout may vary depending on application. These numbers may be modified based on user equipment capability or fabrication criteria. A more robust pattern may be desired for wave soldering and is calculated by adding 0.2 mm to the 'Z' dimension. For further information, please reference document IPC-SM-782, Surface Mount Design and Land Pattern Standard, and for International grid details, please see document IEC, Publication 97.

Figure 4 Dimensions	MiniDIP	DF-S
Z	8.1	11.5
G	4.4	6.9
X	0.9	1.3
Y	1.9	2.
C	6.3	9.2
E	1.3	2.6

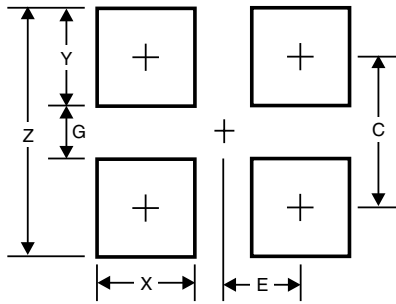


Fig. 4

Figure 5 Dimensions	POWERMITE®3	DPAK	D ² PAK
Z	6.9	11.6	16.9
X1	1.0	1.5	1.1
X2	4.8	7.0	10.8
Y1	0.8	2.5	3.5
Y2	5.3	7.0	11.4
C	3.85	6.9	9.5
E1	0.9	2.3	2.5

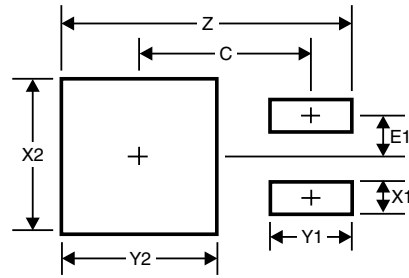


Fig. 5

Figure 6 Dimensions	DO-216AA
Z	2.54
G	0.635
X	2.67
Y	1.27
C	0.762

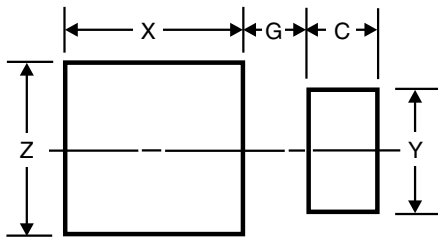


Fig. 6

Figure 7 Dimensions	SOT-143
Z	2.70
G	1.30
X	1.0
Y	0.70
C	2.0
E	0.60
H	2.50

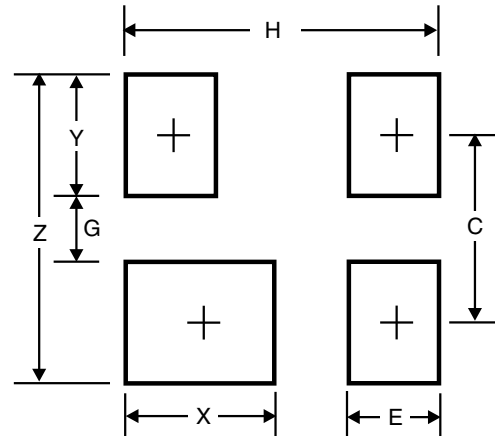


Fig. 7

ALL DIMENSIONS ARE NOMINAL VALUES SHOWN IN MILLIMETERS

Note: The suggested land pattern dimensions have been provided for reference only, as actual pad layout may vary depending on application. These numbers may be modified based on user equipment capability or fabrication criteria. A more robust pattern may be desired for wave soldering and is calculated by adding 0.2 mm to the 'Z' dimension. For further information, please reference document IPC-SM-782, Surface Mount Design and Land Pattern Standard, and for International grid details, please see document IEC, Publication 97.